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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10082174	FILING DATE 02/25/2002	CLASS 257	SUBCLASS 106	GAU 2814	EXAMINER 2814 W. Fanning
**APPLICANTS: Crane Stanford, Alcaran Vicente, Jeon Myoung-Soo					
**CONTINUING DATA VERIFIED: no					
** FOREIGN APPLICATIONS VERIFIED: no					
PG-PUB		DO NOT PUBLISH <input checked="" type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		yes <input type="checkbox"/> no <input checked="" type="checkbox"/>		ATTORNEY DOCKET NO	
35 USC 119 conditions met		yes <input type="checkbox"/> no <input checked="" type="checkbox"/>		040879-5092	
Verified and Acknowledged Examiner's initials		<i>[Signature]</i>			
TITLE: Micro grid array semiconductor die package					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Total Claims	Print Claim for O.G.
		Sheets Drwg.	Figs. Drwg.
			Print Fig.
MINOR DISC AMFR		Application Examiner	
		REPAIRED FOR ISSUE	
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